

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	1002	347/56.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L9	1002	L8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L10	415	347/61.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L11	415	L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L12	419	347/62.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L13	419	L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L14	1285	347/40.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00

L15	591	347/41.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L16	704	347/42.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L17	1647	347/47.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:00
L18	868	9 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L19	348	11 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L20	323	13 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L21	1105	14 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L22	588	15 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01

L23	381	16 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L24	1483	17 not silverbrook. in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:01
L25	134	(areal area) near density same (nozzle orifice) same (substrate wafer chip) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:03
L26	0	18 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:15
L27	0	19 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:15
L28	0	20 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:15
L29	0	21 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:15
L30	0	22 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:16

L31	0	23 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:16
L32	0	24 and 25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:16
L33	15	(ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:17
L34	0	18 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30
L35	0	19 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30
L36	0	20 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30

L37	0	21 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30
L38	0	22 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30
L39	0	23 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:30
L40	0	24 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:31
L41	0	9 and (ink adj jet \$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:31
L42	1	(ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:31

L43	0	18 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L44	0	19 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L45	0	20 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L46	3	21 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L47	0	22 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L48	0	23 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32
L49	0	24 and 33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:32

L50	0	(ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice) same (substrate wafer chip) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:37
L51	13	(ink fluid liquid) near (jet\$3 eject \$3 record\$3 discharge\$3) near (head printhead print adj head) same area near density same (nozzle orifice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:49
L52	1	"347"/\$.ccls. and (ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice). clm.	US-PGPUB	OR	ON	2008/02/05 14:51
L53	14	"347"/\$.ccls. and (ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density same (nozzle orifice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:51
L54	2	(ink adj jet\$3 inkjet\$3) near (head printhead print adj head) same area near density near (nozzle orifice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:52
L55	3	area near density same (nozzle orifice) same (substrate wafer chip) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:54

L56	0	area near density near (nozzle orifice) same (substrate wafer chip) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:55
L57	131	(areal area) near density near (nozzle orifice) same (substrate wafer chip) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 14:55
L58	150	(ink adj jet\$3 inkjet\$3) near (head printhead print adj head) and (areal area) near density near (nozzle orifice) and (wafer chip substrate) near surface	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:12
L70	2	"6669334".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:24
L71	1	("6557977").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 15:24
L72	4	("4914562" "5706041").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:34
L79	2	"5796148".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 18:28

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